

## **AMENDMENT TO THE SPECIFICATION**

**Please replace the paragraph beginning at page 8, line 9, with the following rewritten paragraph:**

Since this invention makes it possible to prevent outer atmosphere above the atmosphere cutoff plate from being involved [[into]] in the selected recovery duct, it is possible to suppress redeposition of the processing solution onto the substrate. Further, since it is possible to prevent a plurality of processing solutions from being mixed in recovery, the recovery can be achieved with high efficiency.